



product feature

- High thermal conductivity low interface thermal resistance and good thixobehavior
- No stress, can be infinitely compressed to the thinnest 0.1mm
- No settlement, no flow, can fill any uneven gap
- Easy design and application, with automatic dispensing machine can adjust any thickness size
- Meet the requirements of ROHS, REACH, UL and other directives

typical application

- Heat dissipation between CPU, GPU, thyristor, wafer and heat sink
- Automotive electronic control, heat transfer between the drive module components and the shell
- Network equipment, portable electronic devices, high-end medical devices, etc.
- New energy vehicle batteries, energy storage equipment, heat pipe cooling modules and other heat transfer areas

Instructions

1. Clean the surface of the adhesive or coated material to remove rust, dust and oil.
2. Manual dispensing, when using, unscrew the mouth cover, connect the mixing tube, and then stick the rubber tube in the bayonet of the AB glue gun, and apply glue vigorously to make the A and B components of the gel body evenly mixed. Place the uniformly mixed gel point in the corresponding position, and wait for the gel to cure.
3. Automatic dispensing, mainly refer to the dispensing machine requirements.
4. The curing time is affected by the ambient temperature, the higher the temperature, the faster the curing.

technical specification

project		unit	standard values		test method
basic parameter	Structural Equation Modds	/	A	B	/
	texture	/	Ceramic particles filled with silicone		/
	colour	/	grey	white	visual inspection
	proportion	g/cc	1.8	1.8	ASTM D792
	press ratio (90psi, 60s)	g/min	30	30	/
	resting period	month	6		/
performance operating	mixing ratio	kg	1:1		/
	ambient cure (25°C)	min	30~60		/
	high temperature setting glue (100°C)	min	20		/
Post-cure parameter	colour	/	grey		visual inspection
	hardness	Shore C	≤30		ASTM D2240
	using temperature range	°C	-50~150		/
	UL fire rating	/	V0		UL 94
	thermal conductivity	w/m.k	1.0±0.2		ASTM D5470
	mass resistivity	Ω.cm	≥2.0*10 ¹²		ASTM D257
	breakdown voltage	KV/mm	≥8.0		ASTM D149

Notes

1. Prevent the mixing of A and B components without use. During the dispensing process, if the dispensing time is too long during the halfway stop, it may cause the colloid in the AB mixing tube to thicken or solidify, and it is not easy to extrude. At this time, it is recommended to replace the hybrid pipe.
2. In case of contact with skin, wipe clean, then rinse with water; In case of contact with eyes, rinse immediately with water and go to hospital for examination.
3. Please refer to the MSDS of the product for safety information.

Storage requirements for satellite

1. This product is non-toxic and non-dangerous goods. It can be handled and transported according to general chemicals.
2. After use, pay attention to sealing and store in a cool, dry and ventilated place.
3. The shelf life of this product in sealed storage is 6 months

packing specification

25+25CC/ PCS, 50+50CC/ PCS, 100+100CC/ PCS, 200+200CC/ PCS

special version

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